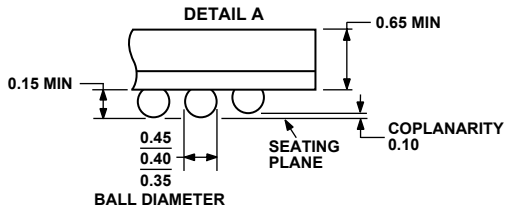
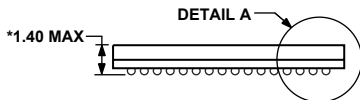
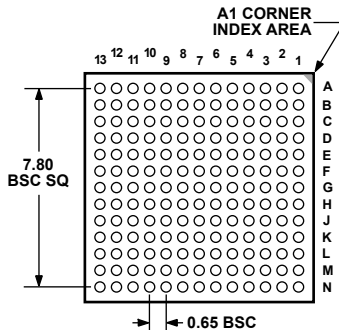
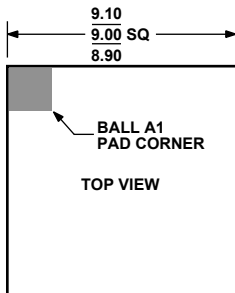


169-Lead Chip Scale Package Ball Grid Array [CSP_BGA]

(BC-169)

Dimensions shown in millimeters

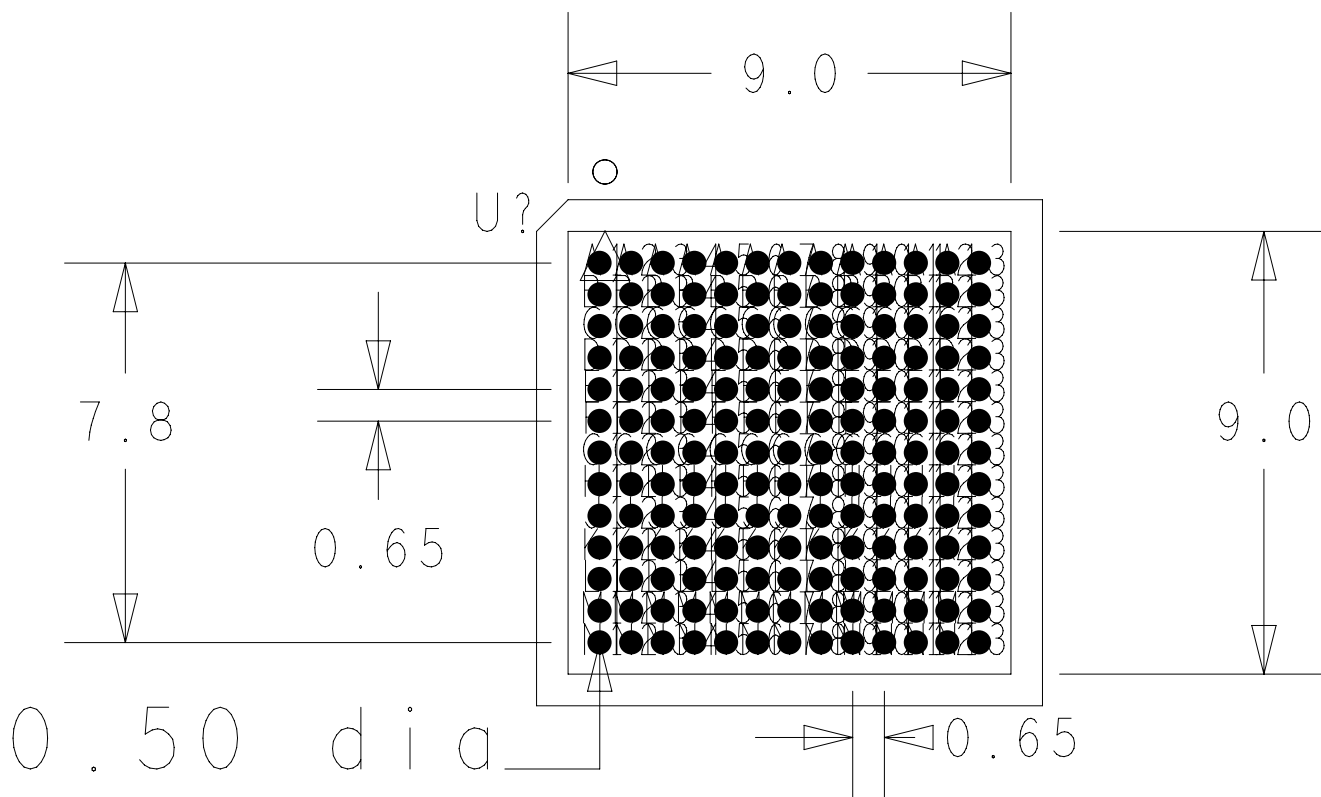


*COMPLIANT TO JEDEC STANDARDS MO-225
WITH THE EXCEPTION TO PACKAGE HEIGHT.

A n a l o g D e v i c e s

B C - 1 6 9

R E V A



(D i m . a r e i n M M)

L A S T M O D I F I E D 0 9 / 1 1 / 0 7